

SID

Factory: Rot am See

Article:

797

ML4

Provided:

Bierlein, Tobias

Customer:

Date:

30.05.2018



Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	A00 B00
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	102		2	
A-RS-FR4-ML-0.10mm-035+035-TG150-HF	50200647	35	L2	3	
		100			
		35	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	102		4	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	5	

Thickness after Pressing

B00:

390 µm

Tol+:

50 µm

Tol-:

50 µm

Dmax:

440 µm

Dmin:

340 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

500 µm

Tol+:

50 µm

Tol-:

50 µm

Dmax:

550 µm

Dmin:

450 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

410 µm

Version 1.2.18.12

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